



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION

Applicant: Leonard J. Gardecki et al. Art Unit:
Serial No.: 10/604164 Examiner:
Filed: 06/28/03 Atty. Docket: BUR920030026US1
Title: METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.56, 1.97, 1.98

Honorable Commissioner of Patents and Trademarks
Washington, D. C. 20231

Sir:

Applicants submit herewith form PTO-1449, listing patents, publications, or other information of which they are aware which they believe may be material to patentability pursuant to 37 CFR 1.56(b), and in respect of which there may be a duty to disclose under 37 CFR 1.56(a), together with legible copies of the patents, publications, or other information listed.

While the items submitted with this Information Disclosure Statement may be material to patentability pursuant to 37 CFR 1.56, in accordance with 37 CFR 1.97(h) it shall not be construed to be an admission that any patent, publication, or other information cited is "prior art" or is material to patentability for this invention unless specifically designated as such. In accordance with 37 CFR 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other information material to patentability, as defined in 37 CFR 1.56(b), exists.

Respectfully submitted,

Date:

Jul. 16, 2003

By:

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(Use several sheets if necessary.)

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FILING

6-28-03

GROUP

U.S. PATENT DOCUMENTS

[illegible][illegible]

			BUR919980169 Document, Mendelson et al., METHOD FOR MOUNTING WAFER FRAME AT BACKSIDE GRINDING (BSG) TOOL, 3/1999, 3 pages.

DATE CONSIDERED

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